

**PART INFORMATION**

Mfg Item Number	MC908QT2ACFQE
Mfg Item Name	QFN-D 8EP 4SQ*1.0P0.8

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2014-10-15
Response Document ID	6165K10737D054A1.17
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

**DECLARATION**

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e3
EU RoHS Exemption(s)	

**MANUFACTURING**

Mfg Item Number	MC908QT2ACFQE
Mfg Item Name	QFN-D 8EP 4SQ*1.0P0.8
Version	ALL
Weight	0.038100
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0008						g				
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Other aromatic amines	-		0.0000449	g	56122	5.6122	1178	0.1178
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00012653	g	158163	15.8163	3320	0.332
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00058367	g	729593	72.9593	15319	1.5319
Epoxy Die Attach		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0000449	g	56122	5.6122	1178	0.1178
Lead Frame Plating	0.0007						g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000014	g	200	0.02	3	0.0003
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.00069986	g	999800	99.98	18369	1.8369
Bonding Wire	0.0001						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0001	g	1000000	100	2624	0.2624
Die Encapsulant	0.0193						g				
Die Encapsulant		Metals	Aluminum, metal	7429-90-5		0.0003022	g	15658	1.5658	7931	0.7931
Die Encapsulant		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00000002	g	1	0.0001	0	0
Die Encapsulant		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.00000002	g	1	0.0001	0	0
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00060438	g	31315	3.1315	15862	1.5862
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00006045	g	3132	0.3132	1586	0.1586
Die Encapsulant		Lead/Lead Compounds	Lead	7439-92-1		0.00000002	g	1	0.0001	0	0
Die Encapsulant		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00010075	g	5220	0.522	2644	0.2644
Die Encapsulant		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.00110803	g	57411	5.7411	29082	2.9082
Die Encapsulant		Glass	Silica, vitreous	80676-86-0		0.01712413	g	887261	88.7261	449464	44.9464
Copper Lead Frame	0.0117						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.0115675	g	988675	98.8675	303608	30.3608
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.0000038	g	325	0.0325	99	0.0099
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.0000117	g	1000	0.1	307	0.0307
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.000117	g	10000	1	3070	0.307
Silicon Semiconductor Die	0.0055						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00011	g	20000	2	2887	0.2887
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.00539	g	980000	98	141469	14.1469

## LINKS

### MCD LINK

Freescale website <http://www.freescale.com>

### GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_ROHS\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf)

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_REACH\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf)

ELV signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_ELV\\_Freescale\\_Reponse.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf)

Conflict Minerals statement [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_CONFLICT\\_METAL\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf)

### FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ [http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON\\_FAQ](http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ)

Technical Service Request [https://www.freescale.com/webapp/servicerequest.create\\_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod](https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod)

### LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v1.1 Form [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/IPC-1752-2\\_v1.1\\_MCD\\_Template.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf)

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MC908QT2ACFQE\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MC908QT2ACFQE_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MC908QT2ACFQE\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MC908QT2ACFQE_IPC1752A.xml)